

Description

The HXY50P02D uses advanced trench technology

to provide excellent $R_{DS(ON)}$, low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.

General Features

V_{DS} = -20V I_D =-50A

 $R_{DS(ON)} < 18 \text{ m}\Omega @ V_{GS}=4.5V$

Application

Battery protection

Load switch

Uninterruptible power supply

Package Marking and Ordering Information

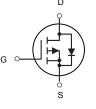
Product ID	Pack	Marking	Qty(PCS)
HXY50P02D	TO252-2L	50P02 XXX YYYY	2500

Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units	
VDS	Drain-Source Voltage	Drain-Source Voltage -20		
VGS	Gate-Source Voltage	Gate-Source Voltage ±12		
I⊳@Tc=25°C	Continuous Drain Current, V _{GS} @ 10V ¹	ous Drain Current, V _{GS} @ 10V ¹ -50		
I⊳@Tc=100°C	Continuous Drain Current, V _{GS} @ 10V ¹	-23	А	
IDM	Pulsed Drain Current ²	-75	А	
P₀@Tc=25°C	Total Power Dissipation ⁴	22	W	
TSTG	Storage Temperature Range	-55 to 150	°C	
TJ	Operating Junction Temperature Range	-55 to 150	°C	
R₀JA	Thermal Resistance Junction-ambient ¹ 75		°C/W	
R₀JC	Thermal Resistance Junction-Case ¹	Thermal Resistance Junction-Case ¹ 4.2		







P-Channel MOSFET



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-20			V
∆BV _{DSS} ∕∆T _J	BV _{DSS} Temperature Coefficient	Reference to 25°C ,I⊳=-1mA		-0.012		V/°C
		V _{GS} =-4.5V , I _D =-10A		12	18	
Rds(on)	Static Drain-Source On-Resistance ²	V _{GS} =-2.5V , I _D =-8A		16	22	mΩ
V _{GS(th)}	Gate Threshold Voltage		-0.4	-0.7	-1.0	V
$ riangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, $I_D=-250uA$		2.94		mV/°C
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-15V , V _{GS} =0V , T _J =25°C			1	uA
Igss	Gate-Source Leakage Current	V _{GS} = ± 12 V , V _{DS} =0V			±100	nA
gfs	Forward Transconductance	V _{DS} =-5V , I _D =-10A		43		S
Qg	Total Gate Charge (-4.5V)			35		
Qgs	Gate-Source Charge	V _{DS} =-10V , V _{GS} =-4.5V , I _D =-10A		5.0		nC
Q_{gd}	Gate-Drain Charge			10		
T _{d(on)}	Turn-On Delay Time			12.0		
Tr	Rise Time	V_{DD} =-10V , V_{GS} =-4.5V ,		40.0		ns
T _{d(off)}	Turn-Off Delay Time	R _G =3.3Ω, I _D =-10A		30		115
T _f	Fall Time			10		
Ciss	Input Capacitance			1400		
Coss	Output Capacitance	V _{DS} =-15V , V _{GS} =0V , f=1MHz		350] pF
Crss	Reverse Transfer Capacitance			300		

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
ls	Continuous Source Current ^{1,4}				-50.0	А
lsм	Pulsed Source Current ^{2,4}	V _G =V _D =0V , Force Current				А
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25°C			-1.2	V
trr	Reverse Recovery Time	IF=-10A , dI/dt=100A/µs ,		27		nS
Qrr	Reverse Recovery Charge	T _J =25℃		17.8		nC

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width \leq 300us , duty cycle $\leq 2\%$

3. The power dissipation is limited by 150°C junction temperature

4. The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.



Typical Characteristics

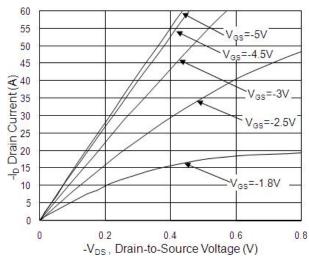


Fig.1 Typical Output Characteristics

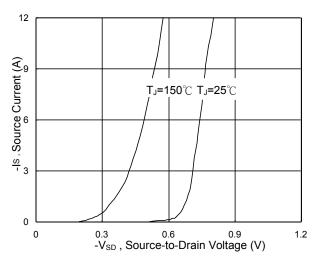


Fig.3 Forward Characteristics of Reverse

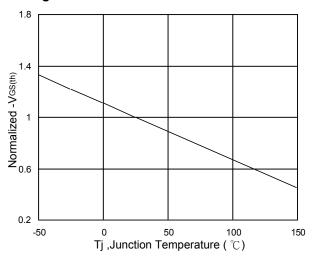


Fig.5 Normalized V_{GS(th)} vs. T_J

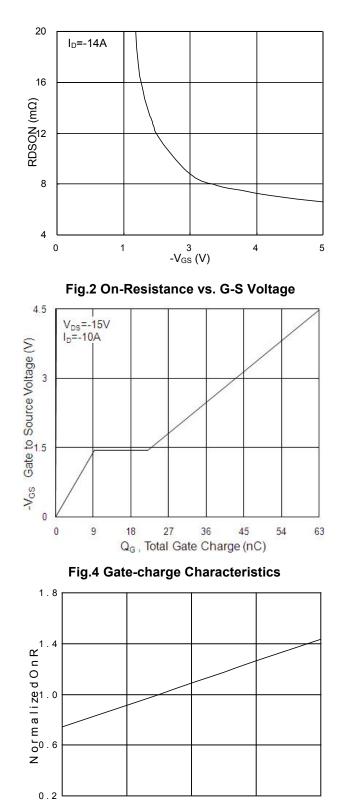


Fig.6 Normalized R_{DSON} vs. T_J

50

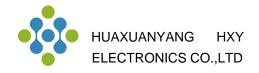
T_J, Junction Temp[®](e)

100

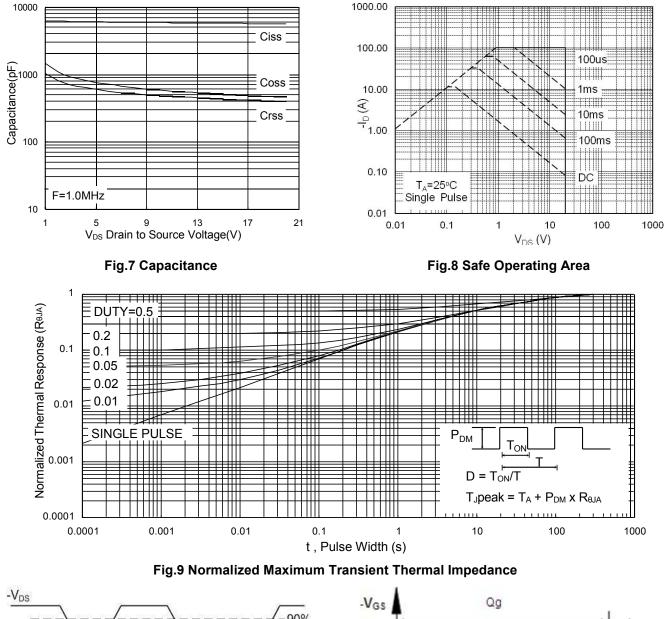
- 5 0

0

150



HXY50P02D P-Channel Enhancement Mode MOSFET



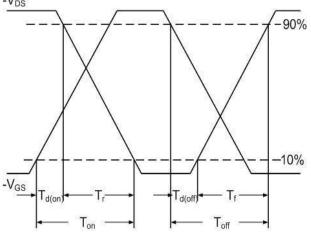


Fig.10 Switching Time Waveform

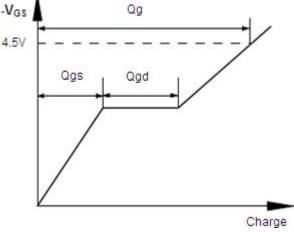
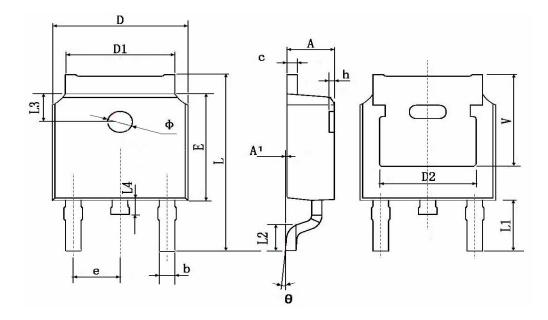


Fig.11 Gate Charge Waveform



TO252-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches			
	Min.	Max.	Min.	Max.		
A	2.200	2.400	0.087	0.094		
A1	0.000	0.127	0.000	0.005		
b	0.660	0.860	0.026	0.034		
С	0.460	0.580	0.018	0.023		
D	6.500	6.700	0.256	0.264		
D1	5.100	5.460	0.201	0.215		
D2	4.830 TYP.		0.190 TYP.			
E	6.000	6.200	0.236	0.244		
е	2.186	2.386	0.086	0.094		
L	9.800	10.400	0.386	0.409		
L1	2.900) TYP.	0.114 TYP.			
L2	1.400	1.700	0.055	0.067		
L3		1.600 TYP.		0.063 TYP.		
L4	0.600	1.000	0.024	0.039		
Φ	1.100	1.300	0.043	0.051		
θ	0 °	8°	0°	8°		
h	0.000	0.300	0.000	0.012		
V	5.350	5.350 TYP. 0.211 TYP.				



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